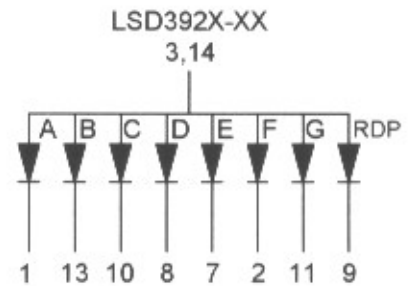
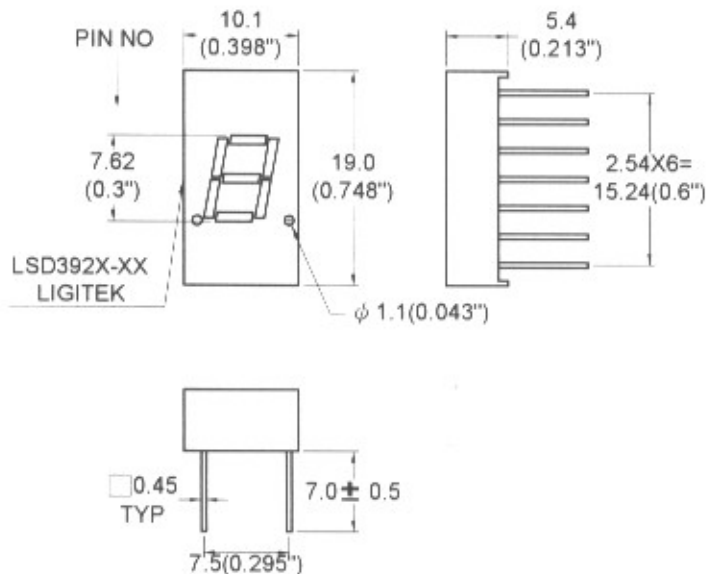




PACKAGE DIMENSION

INTERNAL CIRCUIT DIAGRAM



NOTE: 1. All Dimension Are In Millimeters And (Inch)
 Tolerance Is $\pm 0.25(0.01)$ unless Otherwise Noted
 2. Specifications are subject to change without notice.

• Connection To Electrical Schematic

Electrical connection

PIN NO.	LSD392X-XX	PIN NO.	
1	Cathode A	1	
2	Cathode F	2	
3	Common Anode	3	
4	No Pin	4	
5	No Pin	5	
6	No Pin	6	
7	Cathode E	7	
8	Cathode D	8	
9	Cathode RDP	9	
10	Cathode C	10	
11	Cathode G	11	
12	No Pin	12	
13	Cathode B	13	
14	Common Anode	14	

• Part Selection And Application Information(Ratings At 25°C Ambient)

PART NO	CHIP		common cathode or anode	λ_p (nm)	$\Delta\lambda$ (nm)	Electrical					IV-M
	material	emitted				Vf(v)			Iv(mcd)		
						Min.	Typ.	Max.	Min.	Typ.	
LSD3922-XX	GaP	Green	Common Anode	565	30	1.7	2.1	2.8	2.2	3.7	2:1

• Absolut Maximum Rating (Ta=25°C)

Parameter	Red		Green		Yellow		Orange		Unit	Remark
Forward Current Per Chip				G						
				30					mA	
Peak Current Per Chip (Duty 1/10,0.1mS Pulse Width)				120					mA	
Power Dissipation Per Chip			100						mW	
Derating Linear From 25°C Per Chip			0.45						mA/°C	
Reverse Current Per Any Chip			10						μA	
Operating Temperature	-25°C TO +85°C									
Storage Temperature	-25°C TO +85°C									

Solder Temperature 1-16 Inch Below Seating Plane For 3 Seconds At 260 °C

• Test Condition For Each Parameter

Parameter	Symbol	Unit	Test Condition
Forward Voltage Per Chip	Vf	volt	If=20mA
Luminous Intensity Per Chip	Iv	mcd	If=10mA
Peak Emission Wavelength	λ_p	nm	If=20mA
Spectral Line Half-Width	$\Delta\lambda$	nm	If=20mA
Reverse Current Any Chip	Ir	μA	Vr=5V
Luminous Intensity Matching Ratio	IV-M		